PCN Number: 201		90208000.1		PCN Date:			Feb 1	Feb 13, 2019		
Title: Qualify TI Clark as an additional Assembly site for select devices										
<b>Customer Conta</b>	ct: PCN	<u>Manager</u>	anager Dept:		Quality Services					
Proposed 1 <sup>st</sup> Ship Date:		May 13, 2019			Estimated Sample Availability:			Provided upon Request		
Change Type:										
Assembly Site		jn				Wafer Bump Site				
Assembly Pro		Data Sheet				Wafer Bump Material				
Assembly Mat		Part number change			ge		Wafer Bump Process			
Mechanical Sp				Test Site				Wafer Fab Site		
Packing/Shipp	oing/Label	ing	Test	Test Process				Wafer Fab Materials		
							Wafer	Wafer Fab Process		
			PCN	Details						
Description of C Texas Instruments										
site for the list of				al differen	ces	betwe	en sit	es are a		
Assembly Sit	e Asse	mbly Site C	Drigin	Assemb	ly C	Countr	try Code Assembly City			
UTAC		THA			NSE				Bangkok	
TI Clark		QAB		PHL					Angeles City	
Material Differenc	es:					7				
			JTAC TI			_				
Mount Comp	Mount Compound			4207123	4207123					
Lead finish		NiPdAuAg	uAg NiPdA							
Reason for Chan	ge:									
Continuity of Supp	bly									
Anticipated impa	act on Ma	aterial Decla	aration	ı						
Material Declaration pro rel ob ma		produc releas obtain mater	aterial Declarations or Product Content reports are driven from roduction data and will be available following the production elease. Upon production release the revised reports can be btained from the <u>TI Eco-Info website</u> . There is no impact to the naterial meeting current regulatory compliance requirements ith this PCN change.							
Anticipated impa	act on Fit				or R	Reliabi	lity (	positiv	e / negative):	
None										
Changes to prod	uct iden	tification re	sulting	g from thi	is P	CN:				



## **Qualification Report**

Approve Date 18-Jan-2019

## **Qualification Results**

Data Displayed as: Number of lots / Total sample size / Total failed

Туре	Test Name / Condition	Duration	QBS Product Reference: CC3XXX	QBS Package Reference: 430FR5969IRGZR
ED	Electrical Characterization	Per Datasheet Parameters	Pass	-
HBM	ESD HBM	2000 V	1/3/0	-
CDM	ESD CDM	500V	1/3/0	-
EDR+ HTOL	Life Test, 125C – 100K W/E Endurance cycles followed by 1000 hours HTOL	1000 Hours	2/148/0	-
EDR+ HTSL	High Temp. Storage Bake, 150C– 100K W/E Endurance cycles followed by 1000 hours HTSL	1000 Hours	3/230/0	-
HTSL	High Temp. Storage Bake, 150C	1000 Hours	-	3/229/0
LU	Latch up	(per JESD78)	1/6/0	-
MQ	TEST MQ	-	Pass	Pass
TC	Temperature Cycle, -55/125C	700 Cycles	3/231/0	-
TC	Temperature Cycle, -65/150C	500 Cycles		3/231/0
THB	Biased Temperature & Humidity, 85C/85%RH	1000 Hours	3/77/0	-
BHAST	Biased HAST, 130C/85%RH	96 Hours	-	3/231/0
UHAST	Unbiased HAST, 110C/85%RH	264 Hours	3/231/0	-
AC	Autoclave 121C	96 Hours	-	3/231/0

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/ Green/Pb-free Status: Qualified Pb-Free(SMT) and Green

THIS INFORMATION RELATING TO QUALITY AND RELIABILITY IS PROVIDED "AS IS." Product information detailed in this report may not accurately reflect TI's current product materials, processes and testing used in the construction of the TI products. Customers are solely responsible to conduct sufficient engineering and additional qualification testing to determine whether a device is suitable for use in their applications. Using TI products outside limits stated in TI's datasheet may void TI's warranty. See TI's Terms of Sale at "http://www.ti.com/lsds/ti/legal/termsofsale.page"

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